



Standardized Information for Process/Product Change Notification (PCN)

1. PCN Basic Data		
1.1 Company		Allegro MicroSystems 955 Perimeter Rd, Manchester, New Hampshire 03103
1.2 PCN No.	PbFreeCS	
1.3 Title of PCN	Lead (Pb) Free Conversion - Solder Bumps	
1.4 Customer	AVNET EUROPE	
1.5 Product Category	Active Components – Integrated Circuits	
1.6 Issue Date	19-Jul-2021	
1.7 PCN Revision History (optional)	1.8 Issue Date of Previous Revision (optional)	1.9 Delta to Previous Revision (optional)
NA		

2. PCN Team		
2.1 Contact Supplier		
2.1.1 Name	Heather Brogna	
2.1.2 Phone	603-626-2300	
2.1.3 Email	Hbrogna@allegromicro.com	
2.2 Team Supplier (optional)		
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)

3. Changes			
No.	3.0 Identification	3.1 Category	3.2 Type of Change
#1	SEM-PA-06	PROCESS - ASSEMBLY	Bump Material / Metall System
#2	SEM-PA-14	PROCESS - ASSEMBLY	Change in process technology (e.g. sawing, die attach, bond wire, and form, lead frame preparation)
#3	SEM-PA-15	PROCESS - ASSEMBLY	Process integrity: tuning with
#4			
#5			
#6			
#7			

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#8			
#9			
#10			

4. Description of Change		
	Current	New
Change #1	Current parts utilize leaded (SnPb) solder bumps	New solder bumps will be ma
Change #2	Current parts do not include Epoxy Dotting	Epoxy dotting added to the a
Change #3	Currently no Epoxy Dots	Adding Epoxy Dots to control improving the high voltage is
Change #4		
Change #5		
Change #6		
Change #7		
Change #8		
Change #9		
Change #10		
4.6 Anticipated Impact on Form, Fit, Function, Reliability or Processability?	No anticipated impact to fit, form or function but datasheet specification limits are ir device performance.	
4.7 Reference Parts with Customer Number (optional)		

5. Reason / Motivation for Change	
5.1 Motivation	The European Union (EU) has released Directive 2002/95/EC (RoHS) and requires parts with solder bumps to be lead (Pb) free (previously 7a exen
5.2 Additional Explanation (optional)	

6. Marking of Parts / Traceability of Change	
6.1 Description	Top brand moves from 711 to 711S to signify the SnAg version.

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7. Timing / Schedule			
7.1 Date of Qualification Results			
7.2 Last Order Date (optional)			
7.3 Last Delivery Date (optional)			
7.4 Intended Start of Delivery	2021.11.01		
7.5 Qualification Samples Available?	Yes		
	Date Available	Now	
7.6 Customer Feedback Required Until			
8. Qualification / Validation			
8.1 Description (e.g. qual. plan/report, AEC-Q...)	Qual Data, Q-100		
8.2 Qualification Report and Qualification Results		Issue Date	
9. Input to Customer for Risk Assessment Process			
Under Allegro's procedure for product/process change notification, Allegro strives, based on its technical judgment, to provide notification that may affect form, fit, function, reliability/durability and processability/manufacturability. However, as Allegro cannot ensure evaluation of product in each and every application; the customer retains responsibility to validate the impact of a change on its application suitability.			
10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)			





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w
de from silver (SnAg)
sssembly process
bump height specs and olation performance
creasing to reflect actual

2011/65/EU (RoHS II) which apt).


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of significant changes that product/process changes for